L Number	Hits	Search Text	DB	Time stamp
1	2	6519842.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 08:19
2	24	("4333966" | "4401767" | "4436785" | "4459166" | "4463030" | "4652465" | "4670188" | "4749120" | "4855102" | "4859241" | "5194128" | "5196371" | "5286927" | "5477419" | "5714252" | "5832595" | "5860212" | "5882722" | "5918364" | "5976393" | "5981305" | "6010831" | "6068939" | "6189208" | "2001/0006455").PN.	USPAT	2004/09/16 08:19
3	5	("3486223" | "4208005" | "4314870" | "4345371" | "4582975").PN.	USPAT	2004/09/16 08:22
4	81	IC near mounting and (228/123.1, 156/295 , 228/180.22 , 257/E21.503).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 08:32
5	3	("4249299" | "4835847" | "5045914").PN.	USPAT	2004/09/16 08:36
6	11	("2261015" | "3382564" | "3576969" | "3650454" | "3699640" | "3700156" | "3731867" | "3883945" | "3990863" | "4295596" | "4528746").PN.	USPAT	2004/09/16 08:36
-	2	6510607.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 10:15
-	17	(5793114, 5619017, 5891808, 5612514, 4380042, 4331740, 4331740, "4312926").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:27
-	863	IC and substrate and lead near connecting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 08:32
-	6	IC and substrate and lead near connecting and 29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:30
-	74	IC and substrate and lead near connecting and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:38

-	7	("4862245" | "4948645" | "4994411" | "4997517" | "5041015" | "5086018" | "5108553").PN.	USPAT	2004/09/15 17:33
-	49	4948645.URPN.	USPAT	2004/09/15 17:35
-	16	("4684975" | "4796078" | "4862245" | "4948645" | "4994411" | "4997517" | "5041015" | "5086018" | "5089876" | "5108553" | "5151559" | "5214845" | "5221642" | "5256903" | "5277232" | "5448450").PN.	USPAT	2004/09/15 17:36
-	257	IC and pcb and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:43
-	101	IC near lead and assembly and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 17:50
-	10	("4308339" | "4771330" | "4800419" | "4842662" | "4933741" | "4965702" | "4972253" | "5023202" | "5051813" | "5300481").PN.	USPAT	2004/09/15 17:44
-	8	("3909838" | "4803544" | "4829403" | "4859632" | "5122858" | "5213748" | "5473512" | "5477008").PN.	USPAT	2004/09/15 17:46
-	23	("3902148" | "4050618" | "4054238" | "4224637" | "4271426" | "4331831" | "4380042" | "4514750" | "4531044" | "4584627" | "4642419" | "4725692" | "4759771" | "4814855" | "4862246" | "4920074" | "4980802" | "4982265" | "4985663" | "5018005" | "5064706" | "5121300" | "5137479").PN.	USPAT	2004/09/15 17:48
-	24	("4333966" | "4401767" | "4436785" | "4459166" | "4463030" | "4652465" | "4670188" | "4749120" | "4855102" | "4859241" | "5194128" | "5196371" | "5286927" | "5477419" | "5714252" | "5832595" | "5860212" | "5882722" | "5918364" | "5976393" | "5981305" | "6010831" | "6068939" | "6189208" | "2001/0006455").PN.	USPAT	2004/09/15 17:55

	Title	Current OR
1	Device for dismounting integrated circuit devices	29/743
2	Methods and apparatus for bonding an article to a metallized substrate	228/180.21
3	Integrated-circuit block extraction tool	29/764
4	Method for transferring and joining beam leaded chips	228/176
5	VACUUM DIE SENSOR APPARATUS AND METHOD FOR A SEMICONDUCTOR DIE BONDING MACHINE	228/6.2
6	BONDING HEAD FOR BONDING BEAM LEADED DEVICES TO A SUBSTRATE	228/6.2
7	COMPLIANT BONDING	228/106
8	DEVICE FOR BONDING WITH A COMPLIANT MEDIUM	228/1.1

	Current XRef
1	219/229; 228/264; 228/55; 29/764
2	228/234.1; 228/264; 257/E21.511
3	219/230; 219/85.16; 228/264; 228/51; 29/278; 29/739
4	228/180.21; 228/234.1; 29/827; 29/840
5	228/10; 29/714; 29/827; 29/833
6	228/3.1; 228/45; 29/827
7	228/4.1; 228/5.5; 228/6.2; 269/266; 29/827
8	156/73.1; 228/106; 228/110.1; 228/180.21; 228/234.1; 228/5.5; 269/21; 269/285; 29/827

	Title	Current OR
9	**SOLDER REFLOW DEVICE**	**219/221**
10	**Soldering apparatus and method for microelectronic circuits**	**228/173.5**
11	**Soldering iron**	**219/221**

	Current XRef
9	219/227; 219/237; 219/543; 219/85.16; 228/51; 228/6.2; 29/827; 29/840; 29/846; 338/308
10	219/230; 219/85.15; 228/180.21; 228/191; 228/199; 228/20.1; 228/4.1
11	219/238; 228/55